

IEEE WMED 2026 Technical Program

7:15 - 7:55	Check-In, Registration, and Breakfast (Double R Ranch Room)	
8:00 - 8:10	Welcome Address by General Chair, IEEE WMED 2026	
	Double R Ranch Room Chunhua Yao, Principal Engineer, Micron Technology Inc.	
8:10 - 9:10	Plenary Session	
	Double R Ranch Room, Session Chair: Brian Callaway Visionary Talk Powering the AI Era: Memory Technology at the Center of Compute Scaling Shigeru Shiratake, Senior VP, DRAM Technology and Products Group, Micron Technology Inc.	
9:10 - 10:50	Keynotes Session	
	Double R Ranch Room, Session Chair: Nidish Vashistha Keynote Talk I: Decomposing At-Scale AI Inference: The Where, What, and Why of Memory Technologies Dave Nellans, Senior Director, Architecture Research Group, Nvidia	
	10:00 - 10:50	Keynote Talk II: Hardware Security: The Next Frontier Tamara Schmitz, Director, Product Security Group, Micron Technology Inc.
10:50 - 12:10	Invited Tutorial	
	Double R Ranch Room, Session Chair: Tim Hollis Machine Learning-Based Interface Design for Equalization-Less (or Minimal-Equalization) Channel Compensation Tejasvi Anand, Ramin Javadi, and Jong Hyun (John) Kim, Oregon State University	
12:10 - 13:00	Lunch Break (Double R Ranch and Skyline Room)	
12:10 - 13:00	Poster Session (Double R Ranch)	
13:00 - 13:45	Invited Talk	
	Double R Ranch Room, Session Chair: Mandar S. Bhoir Lithography Technology for Future Computing Technology Michael Lercel, Senior Director, Strategic Marketing, ASML Holding N.V.	
13:45 - 14:40	Panel Discussion	
	Double R Ranch Room, Moderator: Alex Sheldon Hardware Innovation in the AI Era: Memory, Compute and Security Panelists: Tamara Schmitz, Director, Product Security, Micron Technology Inc. Zain Ul Abideen, Assistant Professor, ECE Department, University of Idaho Dave Nellans, Senior Director, Architecture Research Group, Nvidia Corporation	
14:40 - 14:50	Break (Double R Ranch and Skyline Room)	
14:50 - 15:20	Special Talk	
	Double R Ranch Room, Session Chair: Alex Sheldon On-Chip Data-Path Equalization Using Distributed and Interleaved Inverted Feedback Timothy Hollis, Chulkyu Lee and Chris Holub, Micron Technology Inc.	
15:20 - 16:50	Parallel Talks	
	Track 1 (Devices and Process)	Track 2 (Circuits and Systems)
	Double R Ranch Room, Session Chair: Amit Ohri	
	Skyline Room, Chair: Curtis Cahoon	
15:20 - 16:00	Scaling 2D CMOS: From Transistors to 3D Integrated Systems Saptarshi Das, Ackley Professor of Engineering and MRI Fellow, Pennsylvania State Univ.	AI-Driven Design and Synthesis of High-Performance Analog Integrated Circuits Mohamed Elamien, Assistant Professor, McMaster University
16:00 - 16:25	Study of Access Region Sheet Resistance in Superlattice U-GaN HEMT and its Compact Modeling Vikram Magendar and Hiu Yung Wong, San Jose State University	Machine Learning-Based Flaky Test Detection and Suppression for UVM Verification Regressions Vikash Kumar, Yunus Akhtar and Ravi Gupta, Intel Corporation
16:25 - 16:50	Design Tradeoffs of Through-Silicon-Carbide Vias for High-Temperature 3D SiC IC Integration Sahithi Thota, Li Song and Feng Li, University of Idaho	Validation Proportion Matters: Generalization Stability of YOLO-Based Wafer Defect Detection with Limited Data Chih-Kuan Ho and David Parent, San Jose State University
17:00 - 17:10	Closing Remarks by General Chair - Announcement of Poster Winners, End-of-Conference Raffle Winners, and WMED 2027	